

PATENT ASSIGNMENT COVER SHEET

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Stylesheet Version v1.2

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SANG WON LEE	05/15/2014
YANG SEOK KI	05/15/2014
RECEIVING PARTY DATA	
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State/Country:	REPUBLIC OF KOREA
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14281453
CORRESPONDENCE DATA	
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Correspondent Name:	CONVERGENT LAW GROUP LLP
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Address Line 4:	MOUNTAIN VIEW, CALIFORNIA 94043
ATTORNEY DOCKET NUMBER:	MSAL006US
NAME OF SUBMITTER:	DEBBIE NISHIHARA
SIGNATURE:	/Debbie Nishihara/
DATE SIGNED:	05/19/2014
	This document serves as an Oath/Declaration (37 CFR 1.63).
Total Attachments: 4	
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source=MSAL006US_Assignment_AsFiled_5_19_14#page2.tif	
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source=MSAL006US_Assignment_AsFiled_5_19_14#page4.tif	

DECLARATION AND ASSIGNMENT FOR PATENT APPLICATION
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Title of Invention: **HYBRID BUFFER MANAGEMENT SCHEME FOR IMMUTABLE PAGES**

As a below named inventor, I hereby declare that:

This declaration is directed to the attached application, or (if following box is checked):

US Application or PCT Application No. 14/281,453 filed on 5/19/2014

The above-identified application was made or authorized to be made by me.

I believe I am the original inventor (if only one name is listed below) or an original joint inventor (if plural names are listed below) of the subject matter which is claimed.

I have reviewed and understand the contents of the above-identified specification, including the claims.

I acknowledge the duty to disclose all information which is material to patentability as defined in 37 CFR 1.56, including for continuation-in-part applications, material information which became available between the filing date of the prior application and the national or PCT international filing date of the continuation-in-part application.

For good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned inventor(s), do hereby sell, assign, and transfer to: Samsung Electronics Co., Ltd., a corporation having a principal place of business at 129, Samsung-ro, Yeongtong-gu, Suwon-si, Gyeonggi-do, Korea 443-742 ("Assignee"), its successors, assigns, and legal representatives, the entire right, title and interest for the United States and all foreign countries, in and to any and all improvements which are disclosed in the above-identified application and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be issued in the United States and all foreign countries on said improvements; and in and to all rights of priority resulting from the filing of said United States application; and

Each of the undersigned inventors agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

And the Assignors hereby authorize and request the attorneys and agents to insert in the spaces provided above the title of the invention, filing date, application number, and attorney's docket number of said application when known.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and acknowledge that willful false statements and the like so made are punishable under Section 1001 of Title 18 of the United States Code by fine or imprisonment of not more than five (5) years, or both.

DECLARATION FOR PATENT APPLICATION (continued)

Full Name of Inventor: Sang Won Lee

Signature

Date

Full Name of Inventor: Yang Seok Ki



Signature

05/14/2014
Date

DECLARATION AND ASSIGNMENT FOR PATENT APPLICATION

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Each of the undersigned inventors agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

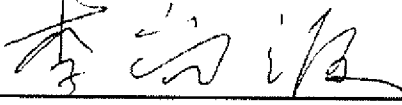
Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

And the Assignors hereby authorize and request the attorneys and agents to insert in the spaces provided above the title of the invention, filing date, application number, and attorney's docket number of said application when known.

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DECLARATION FOR PATENT APPLICATION (continued)

Full Name of Inventor: Sang Won Lee


Signature

15 May 2014
Date

Full Name of Inventor: Yang Seok Ki

Signature

Date